

SCHEMATIC CONTENTS

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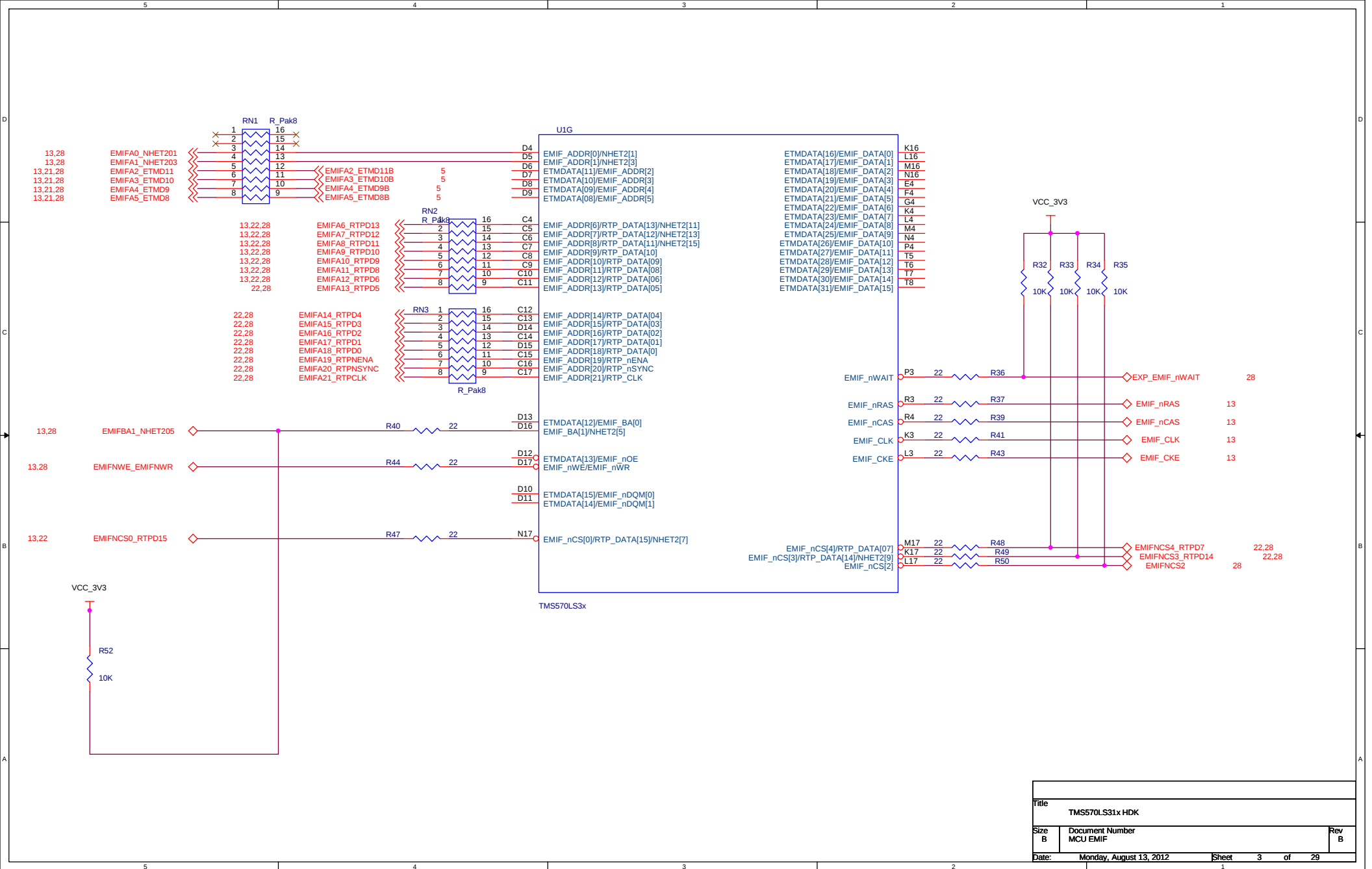
1. Changed SD card slot
2. R291 and R293 value for Gladiator 1.2V core power
3. Route EMIF D[8:15] to exp connector (missed on RevB)

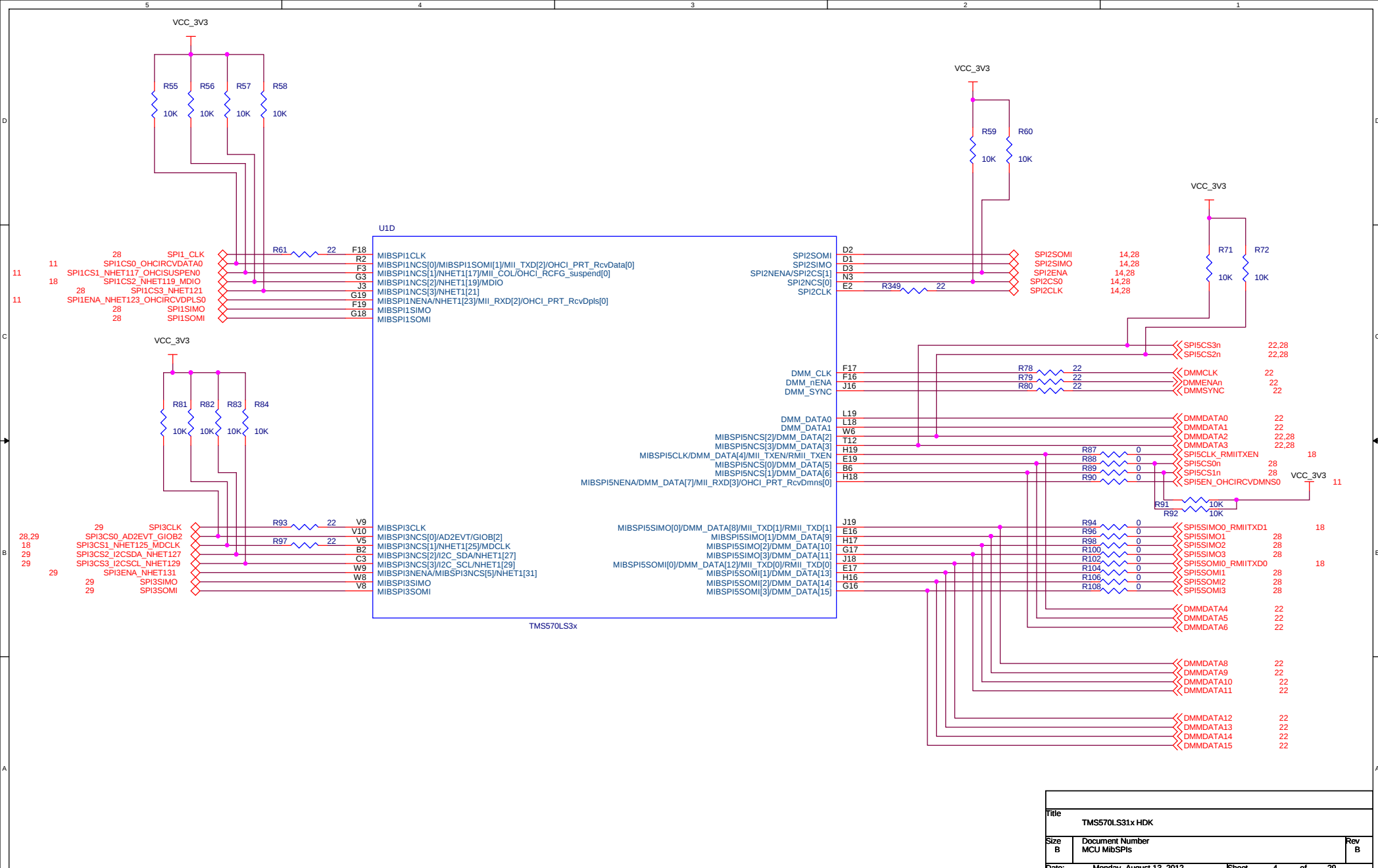
1. Added n\_channel FET and RC to JTAG nTRST (P07)

1. Added n\_channel FET and RC to JTAG nTRST (P07)
2. Replaced 2 color LEDs with 2 white LEDs

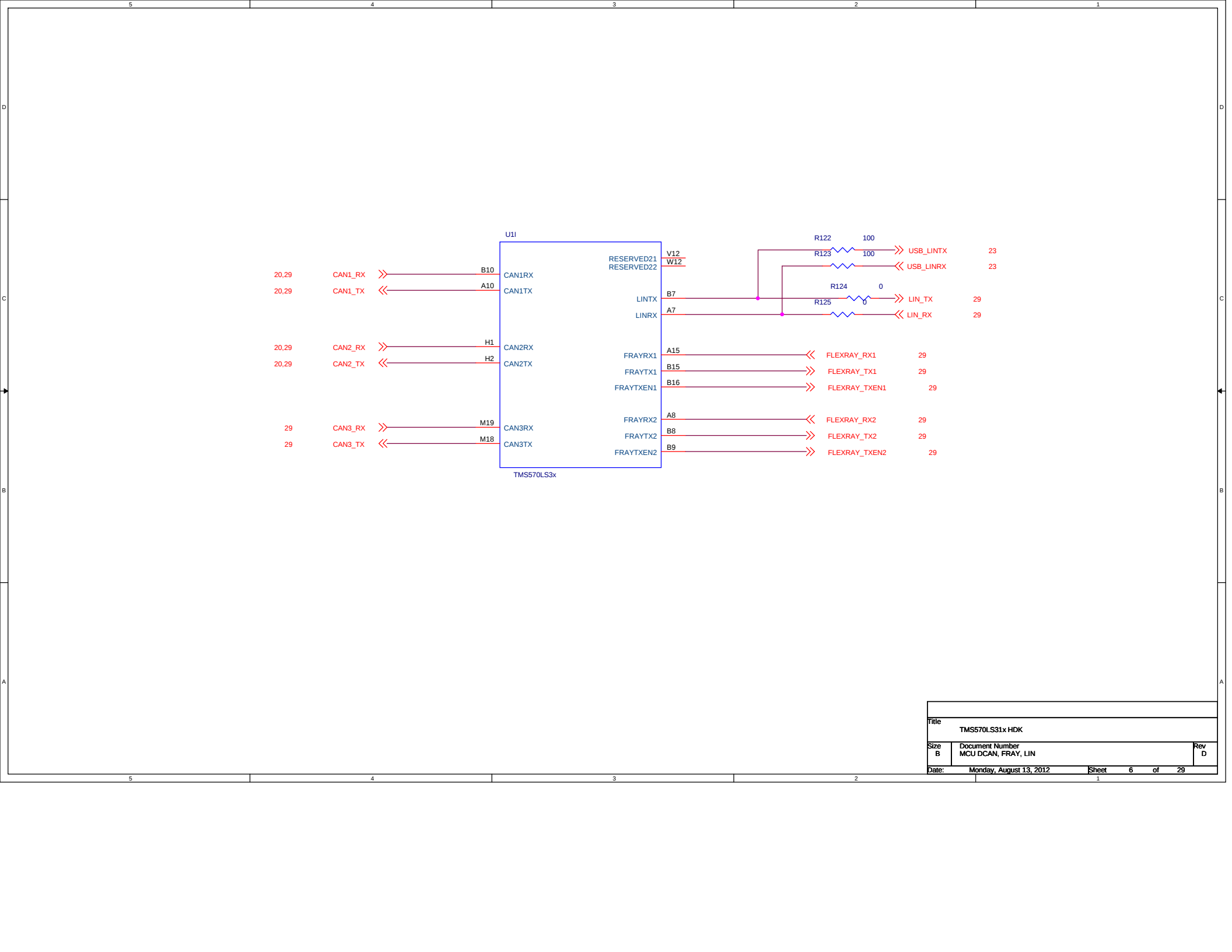
|                              |                          |               |          |
|------------------------------|--------------------------|---------------|----------|
| <b>Texas Instruments Inc</b> |                          |               |          |
| Title<br>TMS570LS31x HDK     |                          |               |          |
| Size<br>A                    | Document Number<br>TITLE |               | Rev<br>B |
| Date:                        | Monday, July 29, 2013    | Sheet 1 of 29 |          |





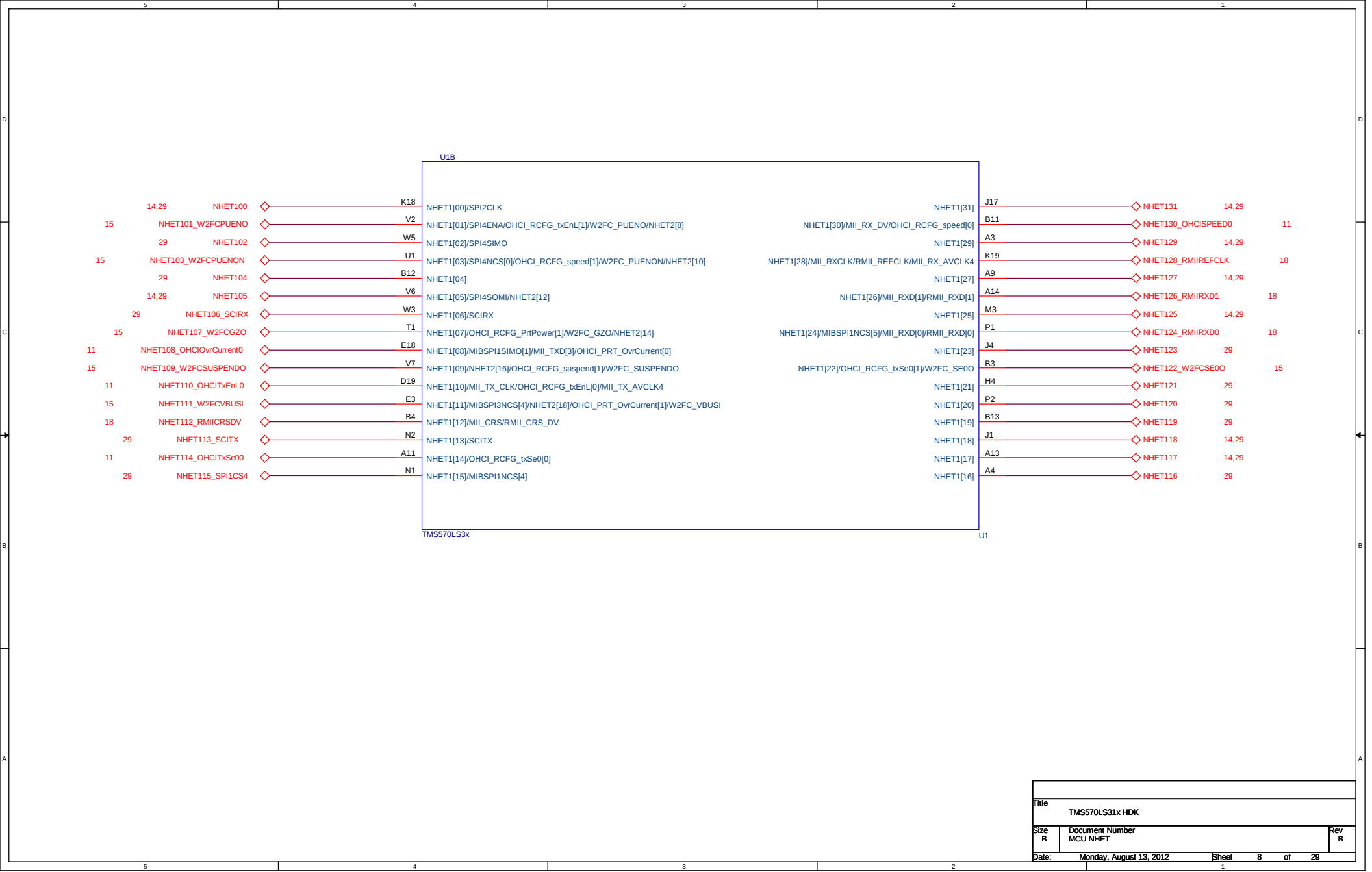


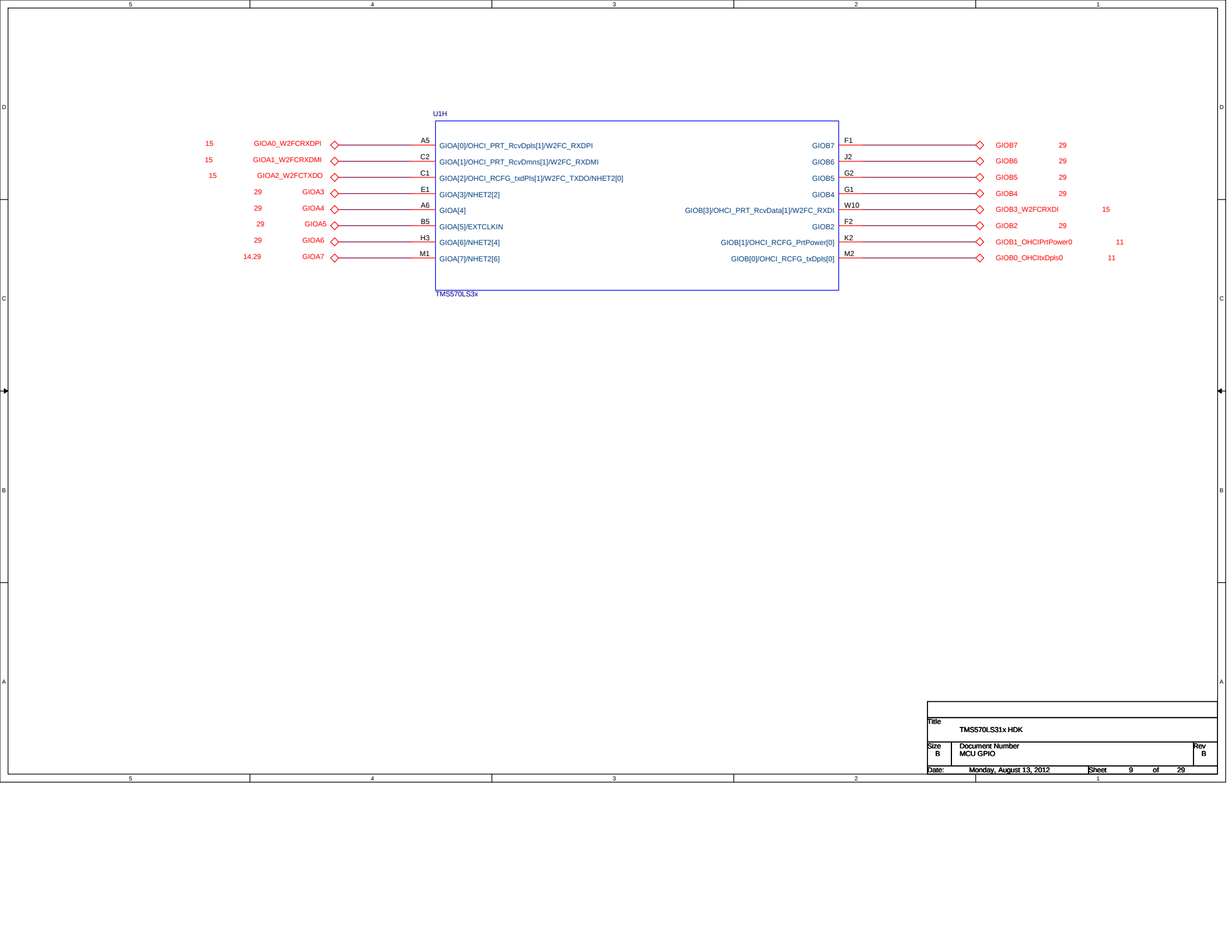


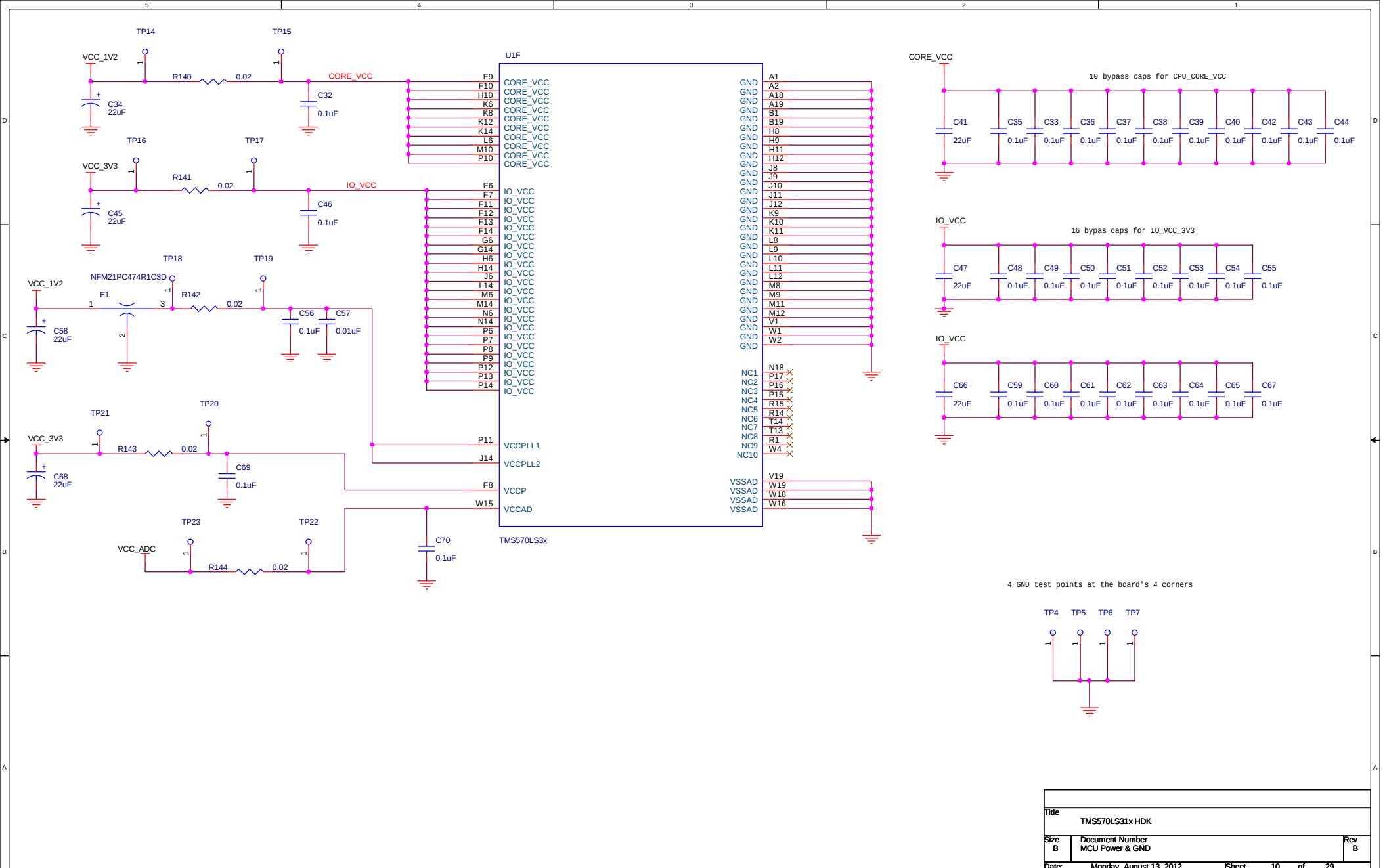


|       |                         |                 |                     |   |       |
|-------|-------------------------|-----------------|---------------------|---|-------|
| Title |                         |                 | TMS570LS31x HDK     |   |       |
| Size  | B                       | Document Number | MCU DCAN, FRAY, LIN |   |       |
| Date: | Monday, August 13, 2012 |                 | Sheet               | 6 | of 29 |





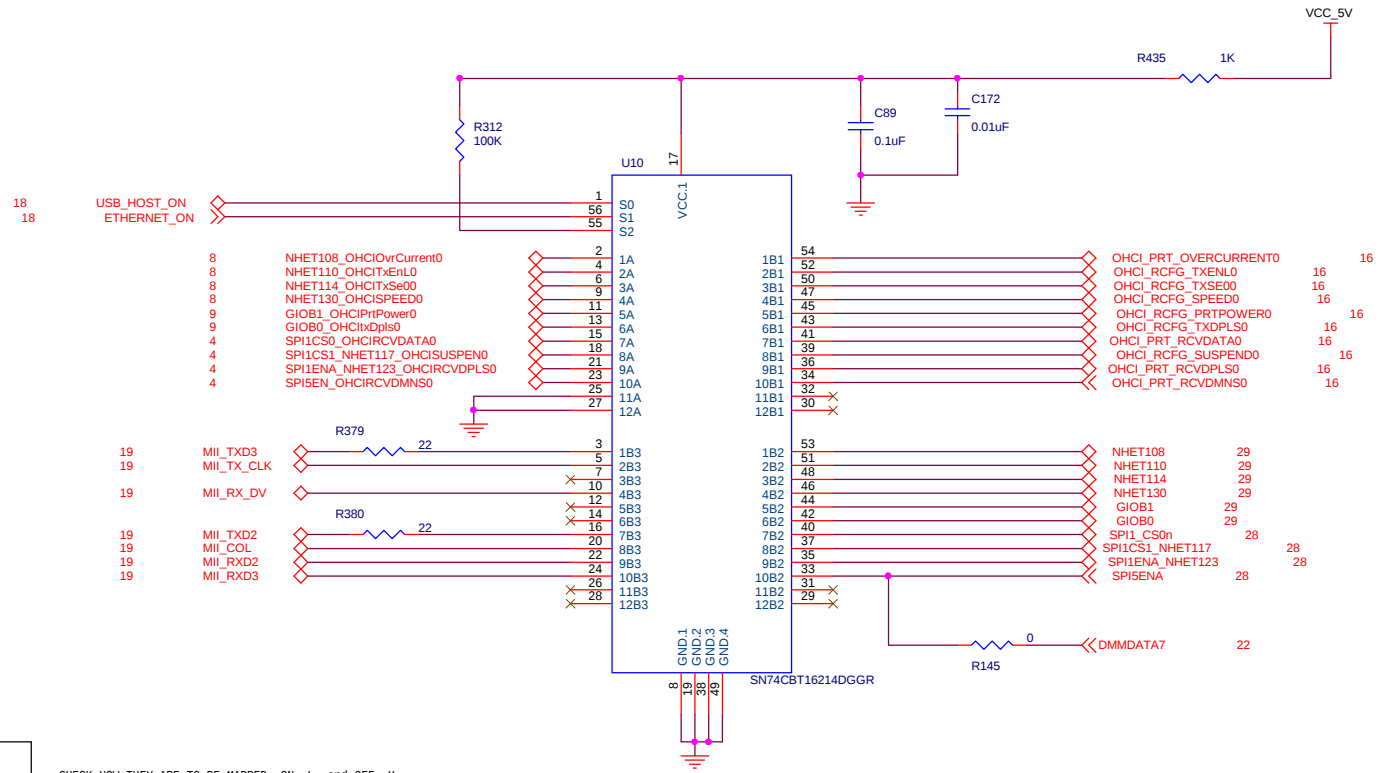




|       |                         |                 |                 |    |       |
|-------|-------------------------|-----------------|-----------------|----|-------|
| Title |                         |                 | TMS570LS31x HDK |    |       |
| Size  | B                       | Document Number | MCU Power & GND |    | Rev B |
| Date: | Monday, August 13, 2012 |                 | Sheet           | 10 | of 29 |

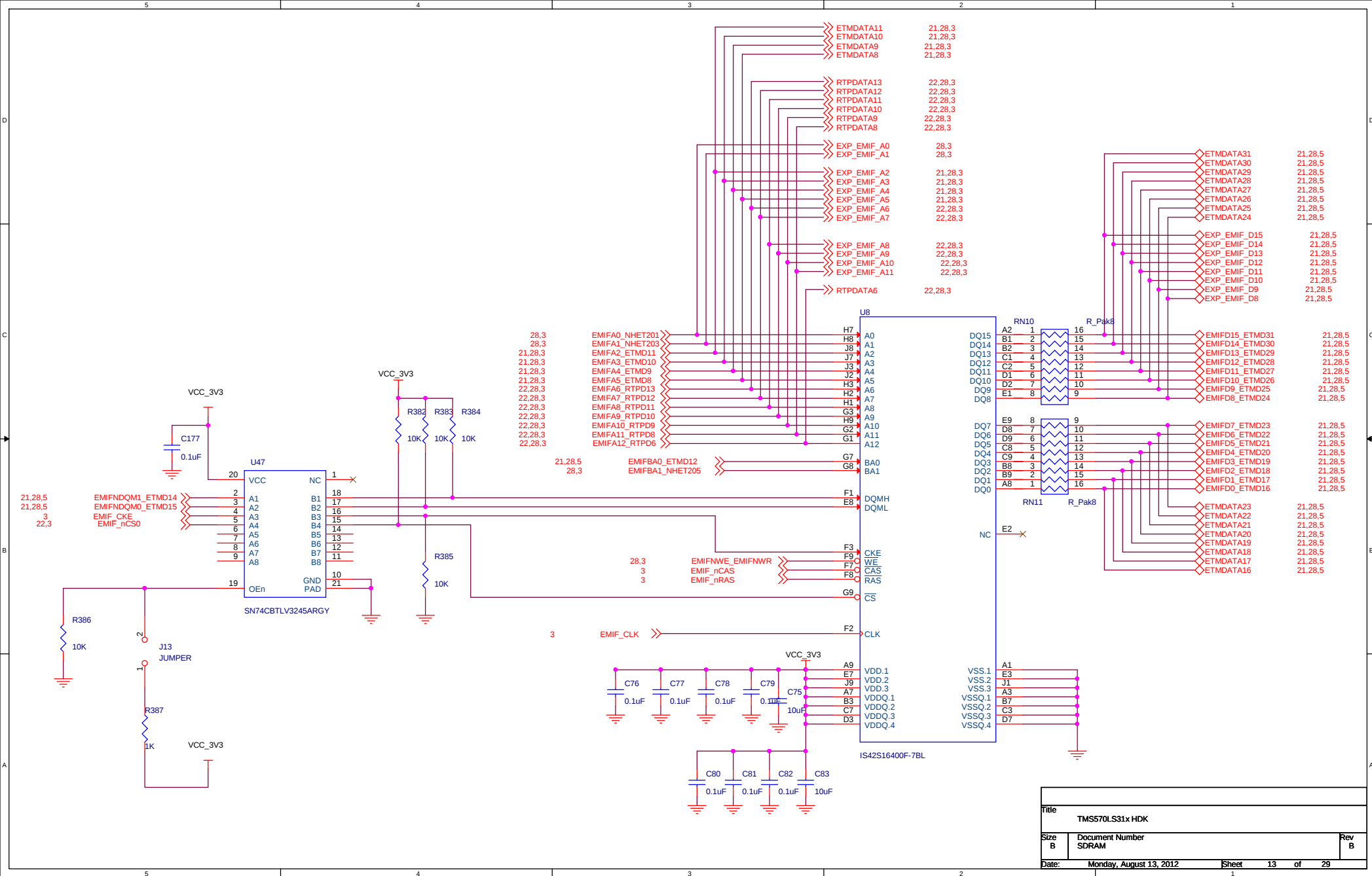
| S2 | S1 | S0 | A     |
|----|----|----|-------|
| 1  | 0  | 0  | Z     |
| 1  | 0  | 1  | B3**  |
| 1  | 1  | 0  | B1 ** |
| 1  | 1  | 1  | B2 ** |

CHECK HOW THEY ARE TO BE MAPPED. ON--L, and OFF--H

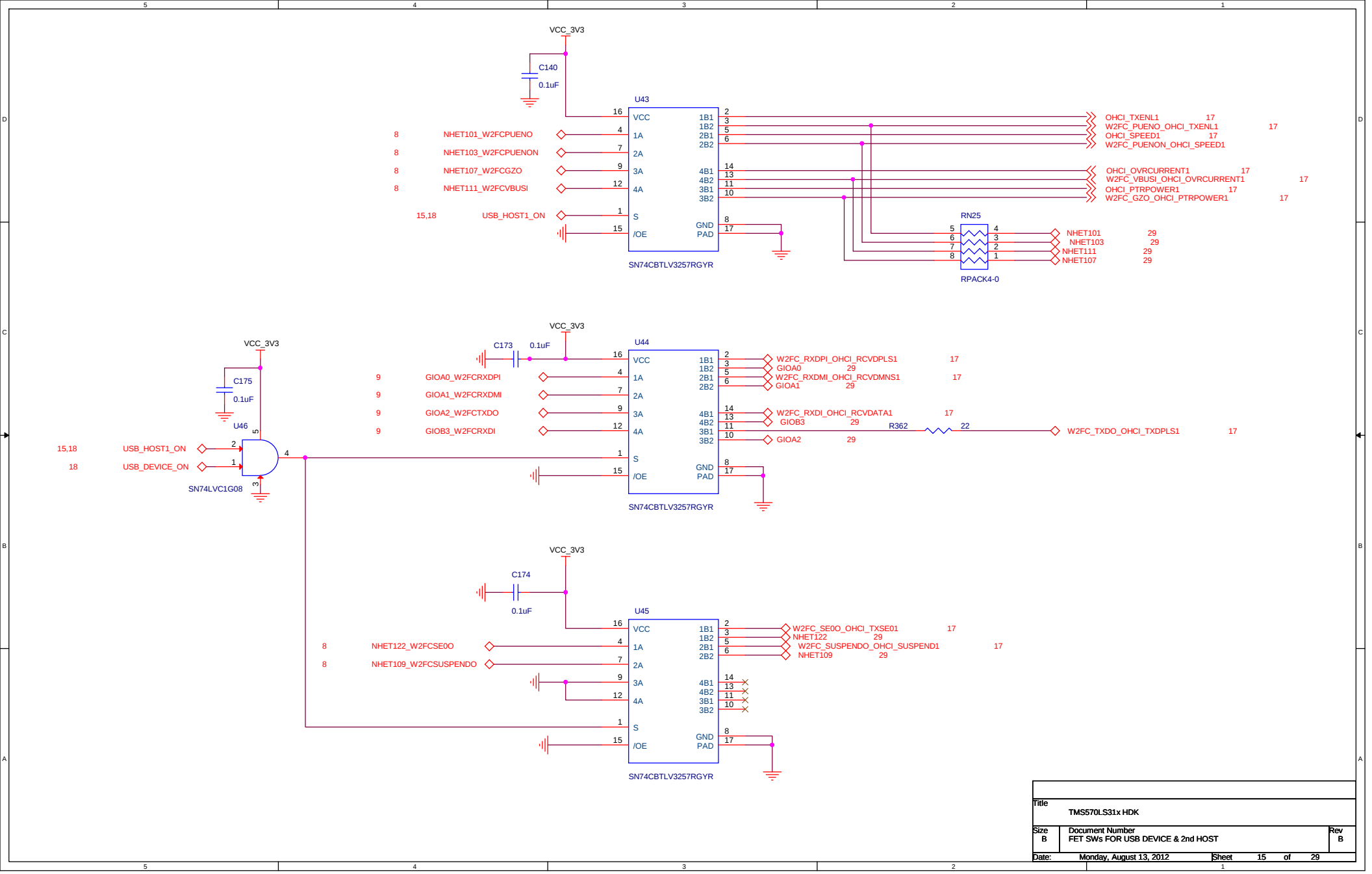


|       |                          |       |                 |
|-------|--------------------------|-------|-----------------|
| Title |                          |       | TMS570LS31x HDK |
| Size  | Document Number          | Rev   |                 |
| B     | FET SWs FOR 1st USB HOST | B     |                 |
| Date: | Monday, August 13, 2012  | Sheet | 11 of 29        |

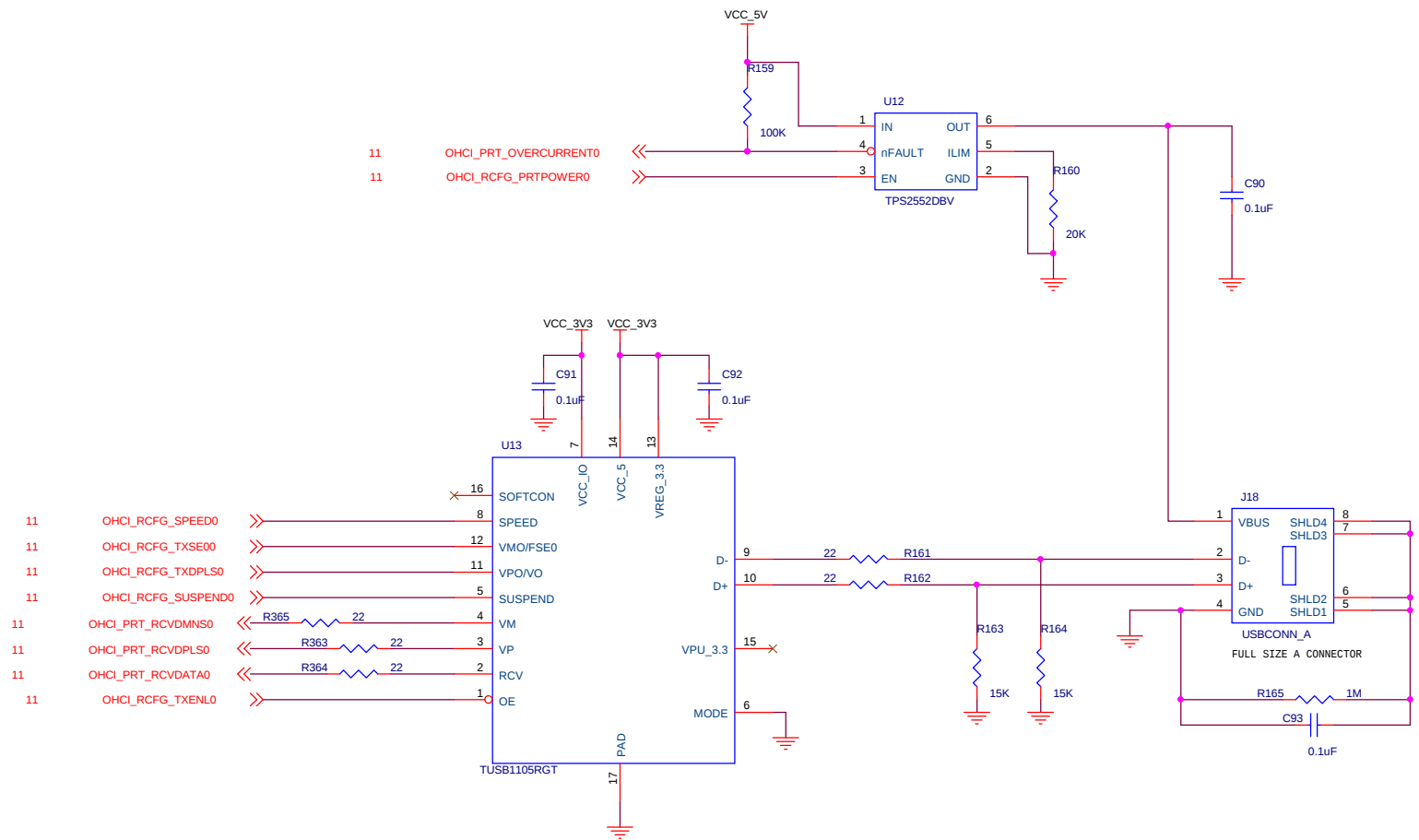




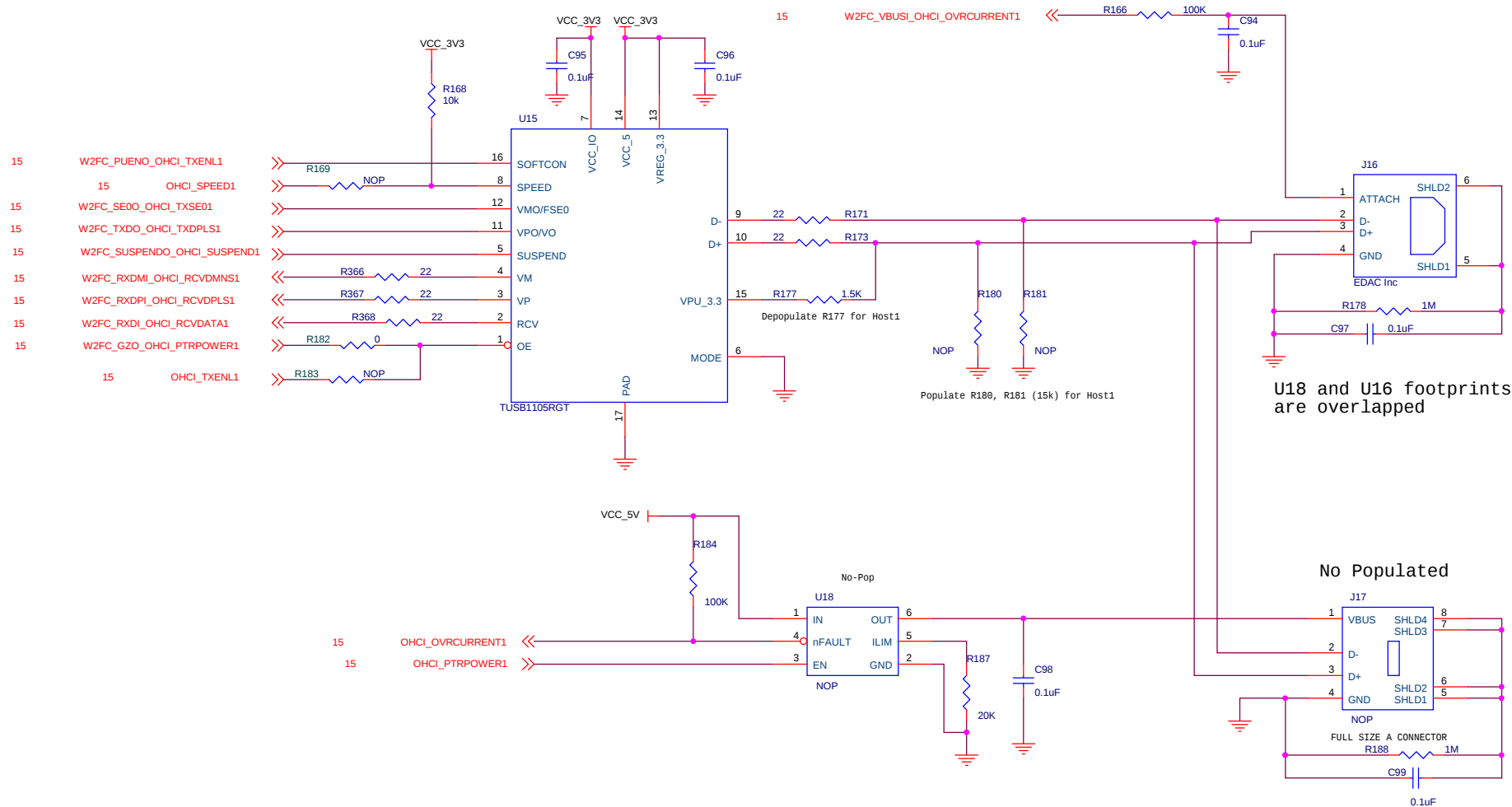




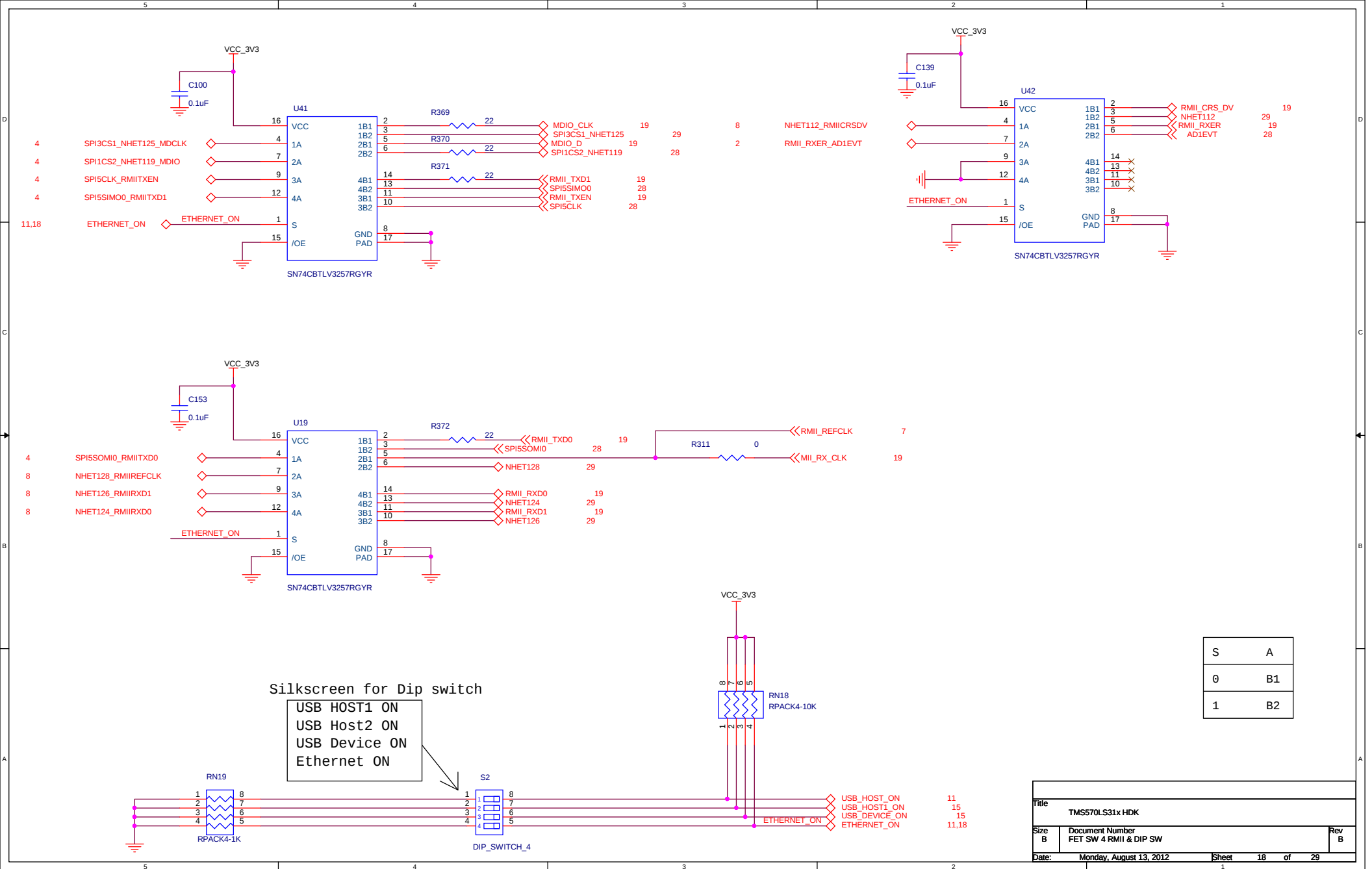
|       |                         |                                   |                 |    |       |
|-------|-------------------------|-----------------------------------|-----------------|----|-------|
| Title |                         |                                   | TMS570LS31x HDK |    |       |
| Size  | Document Number         | FET SWs FOR USB DEVICE & 2nd HOST |                 |    | Rev   |
| B     |                         |                                   |                 |    | B     |
| Date: | Monday, August 13, 2012 |                                   | Sheet           | 15 | of 29 |

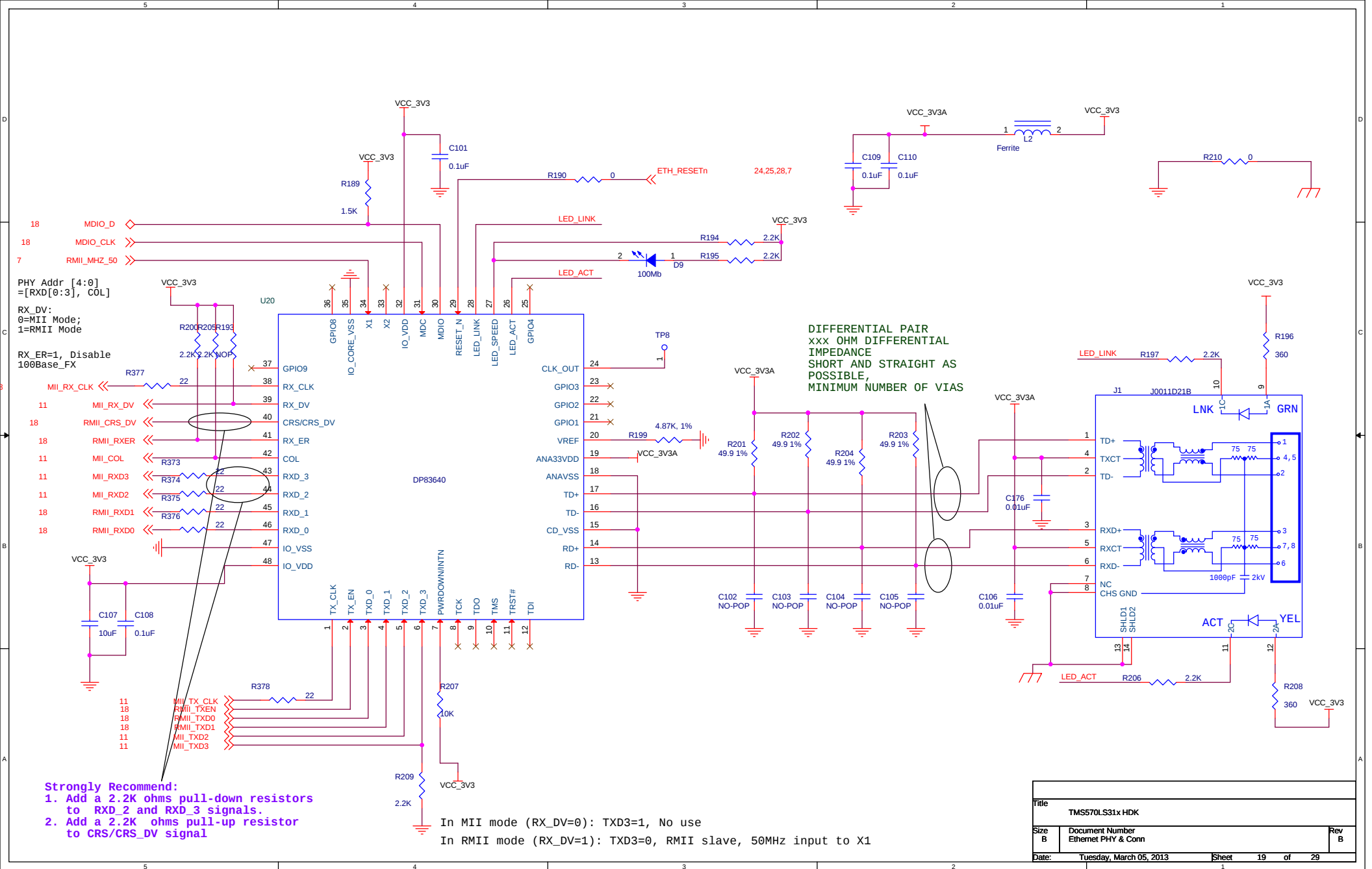


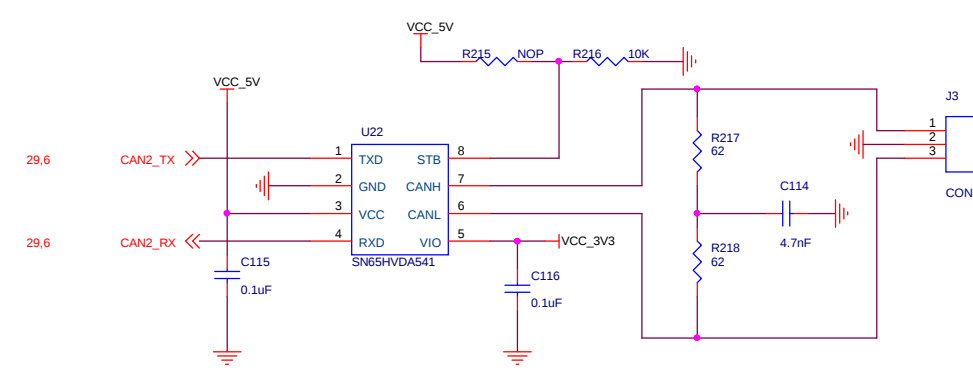
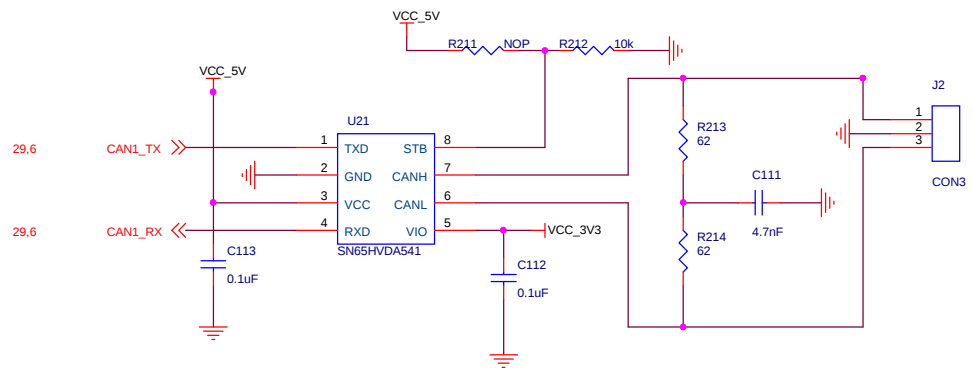
|                 |                         |                |
|-----------------|-------------------------|----------------|
| Title           |                         |                |
| TMS570LS31x HDK |                         |                |
| Size            | Document Number         | Rev            |
| B               | USB 1st OHCI Host       | B              |
| Date:           | Monday, August 13, 2012 | Sheet 16 of 29 |



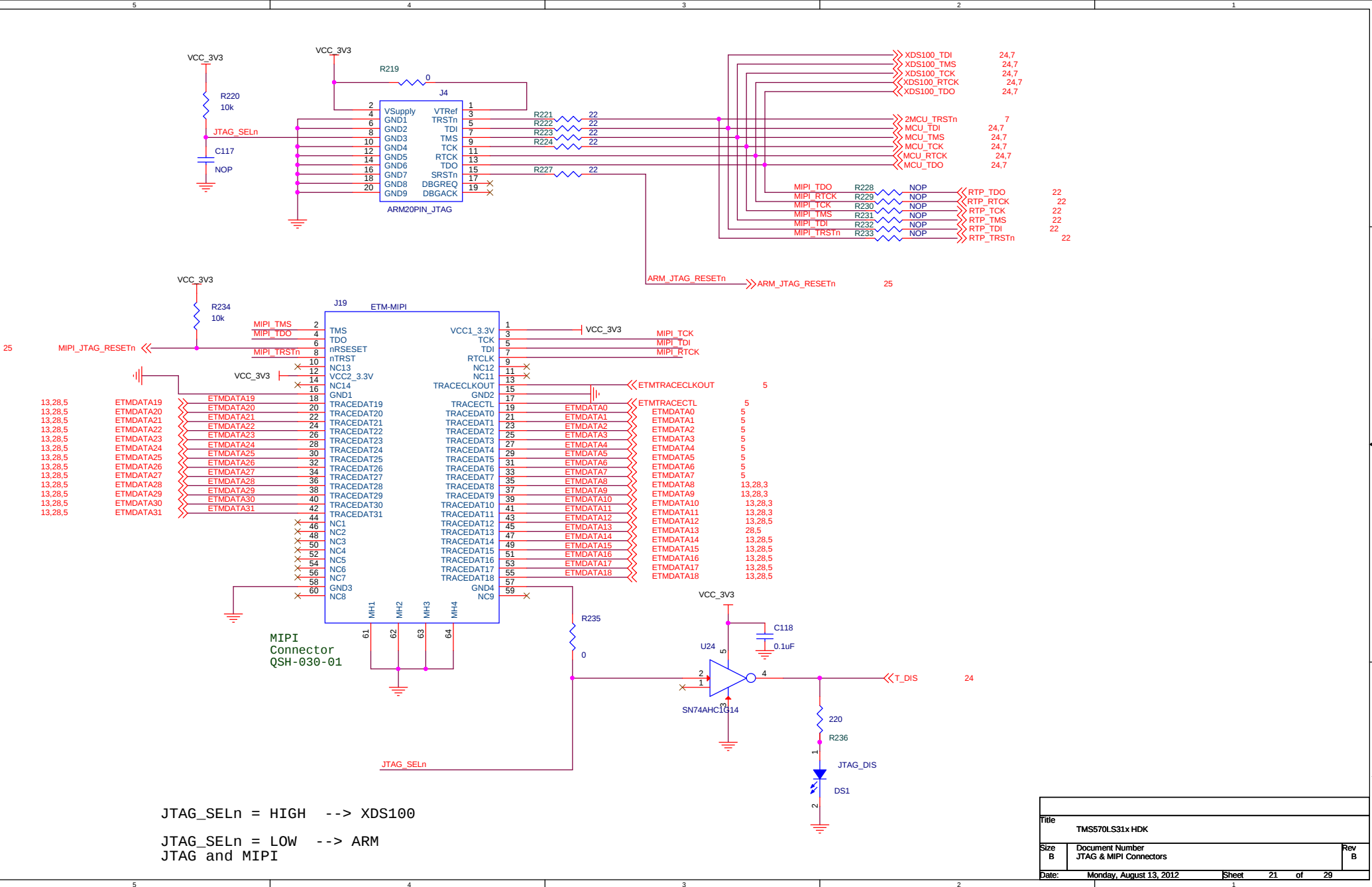
|                       |                         |                |
|-----------------------|-------------------------|----------------|
| Title                 |                         |                |
| TMS570LS31x HDK       |                         |                |
| Size B                | Document Number         | Rev B          |
| USB Device & 2nd HOST |                         |                |
| Date:                 | Monday, August 13, 2012 | Sheet 17 of 29 |

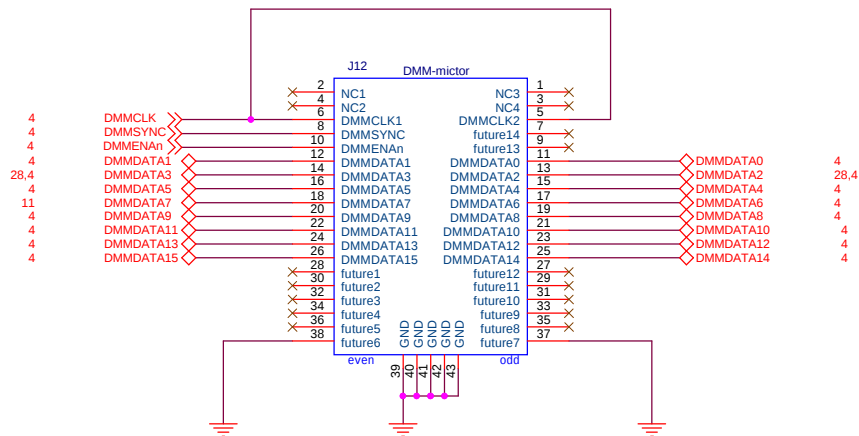




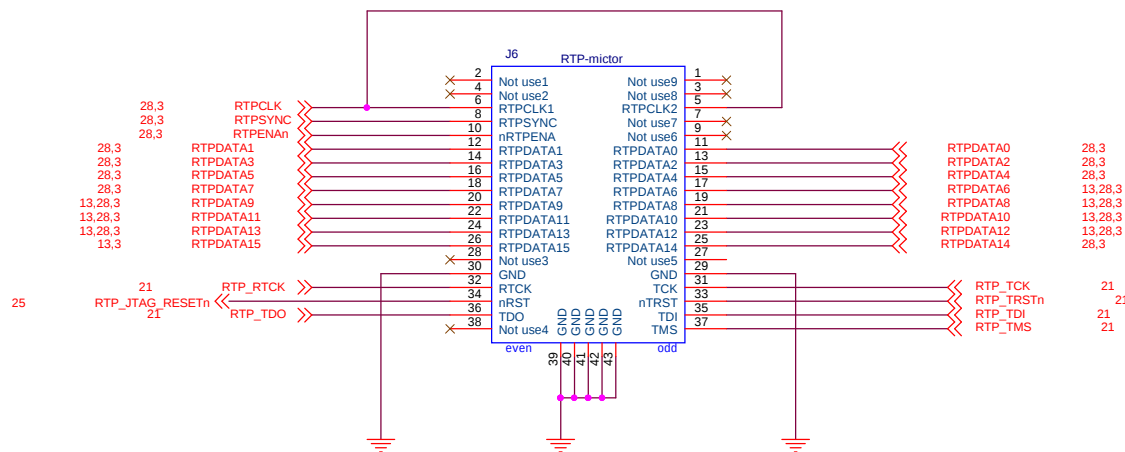


|        |                                   |  |                 |    |       |
|--------|-----------------------------------|--|-----------------|----|-------|
| Title  |                                   |  | TMS570LS31x HDK |    |       |
| Size B | Document Number DCAN Transceivers |  |                 |    | Rev B |
| Date:  | Monday, August 13, 2012           |  | Sheet           | 20 | of 29 |



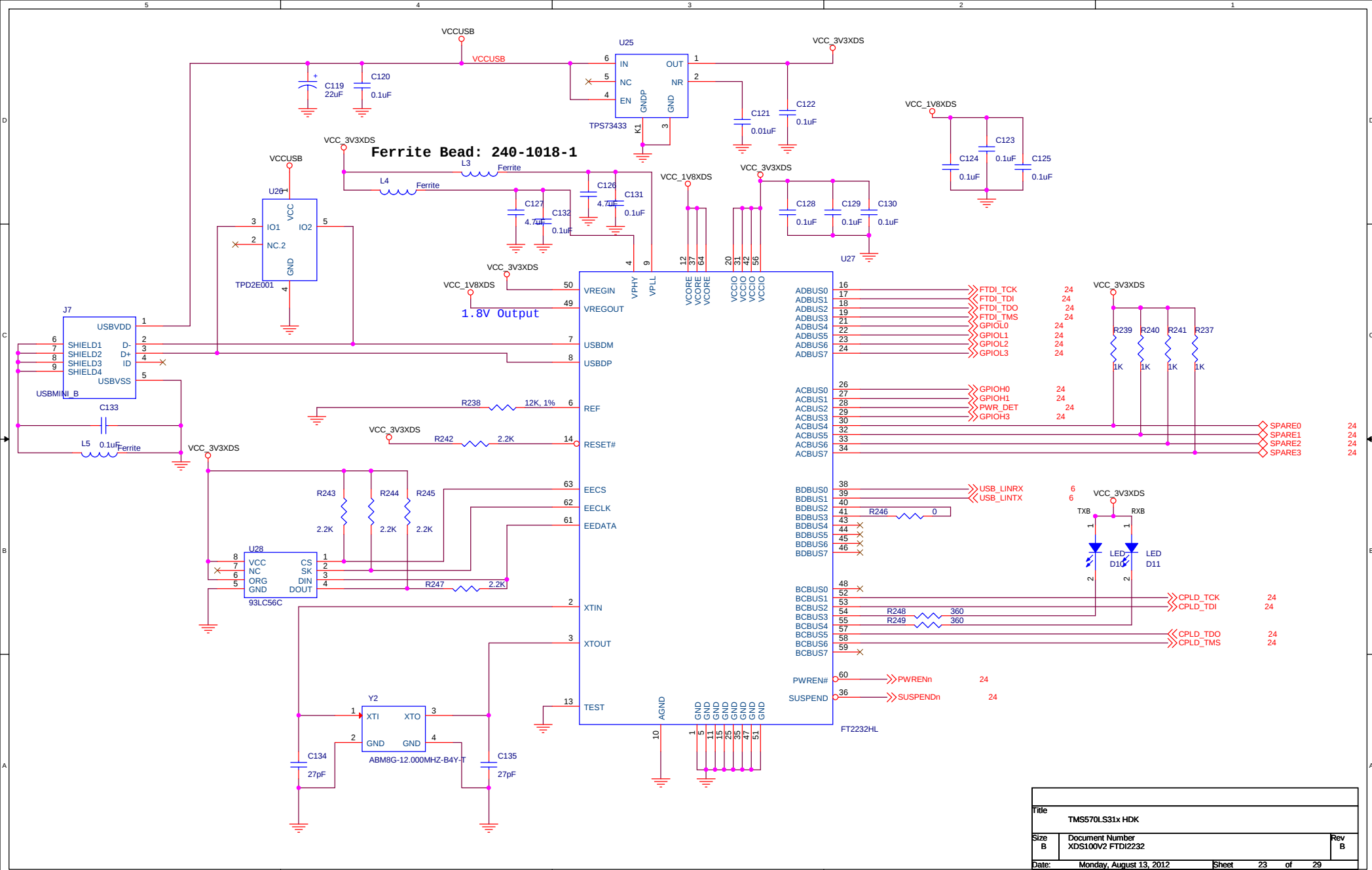


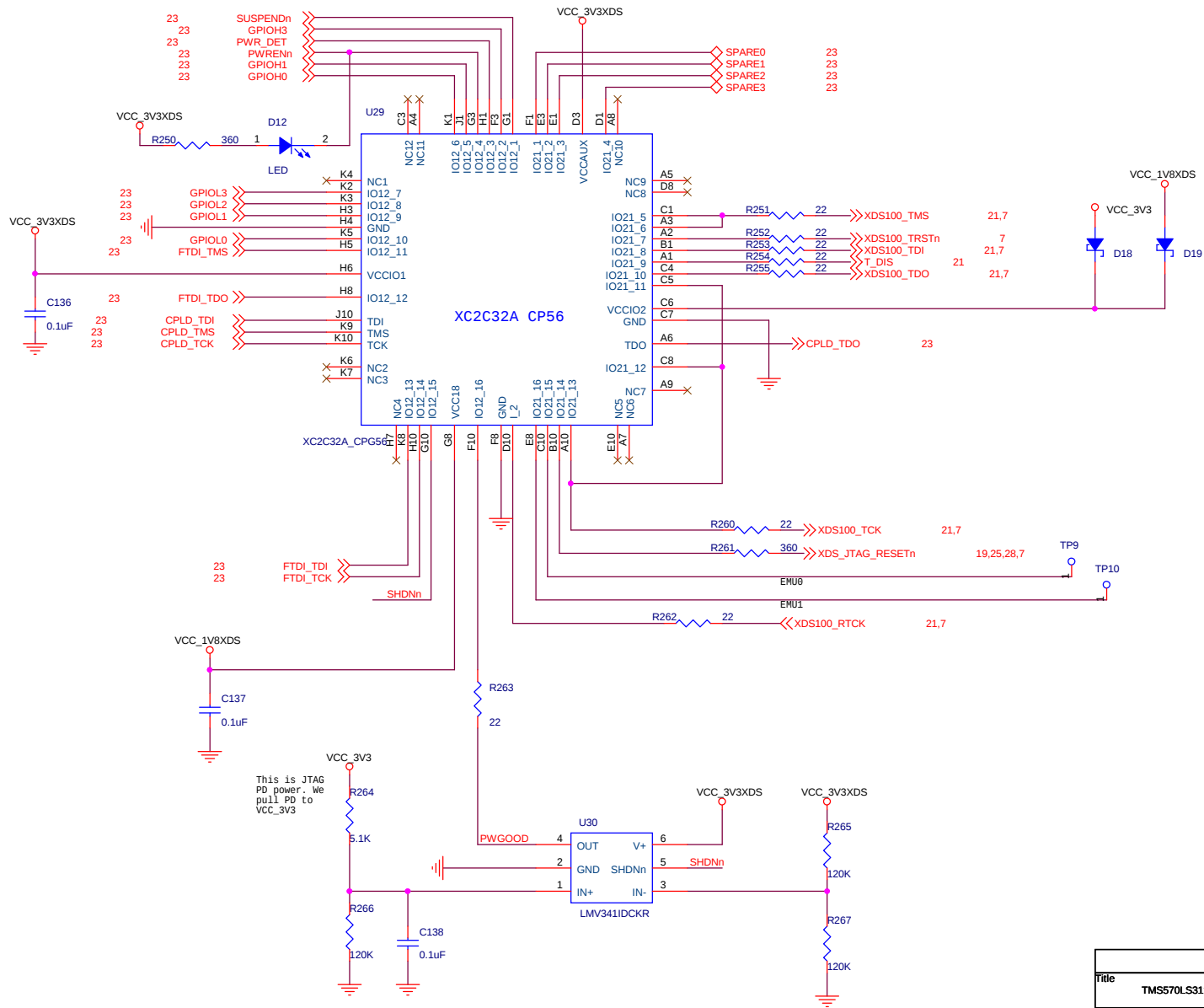
Foot Print Only  
Pin39/40/41/42/43 are the central GND



AMP 2-5767004-2  
Receptacle, Center Strip Contacts  
Foot Print Only

|                          |                      |                |
|--------------------------|----------------------|----------------|
| Title                    |                      |                |
| TMS570LS3x/RM5x CPU CARD |                      |                |
| Size B                   | Document Number      | Rev B          |
| DMM and RTP Connectors   |                      |                |
| Date:                    | Friday, May 18, 2012 | Sheet 22 of 29 |





|                               |                 |     |
|-------------------------------|-----------------|-----|
| Title                         |                 |     |
| TMS570LS31x HDK               |                 |     |
| Size                          | Document Number | Rev |
| B                             | XDS100V2 CPLD   | B   |
| Date: Monday, August 13, 2012 |                 |     |
| Sheet 24 of 29                |                 |     |

If VCC\_3.3V below 3.0V --> RESET

This is the  
RESET pin rather  
than TRST

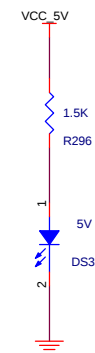
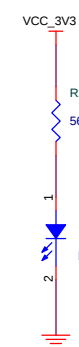
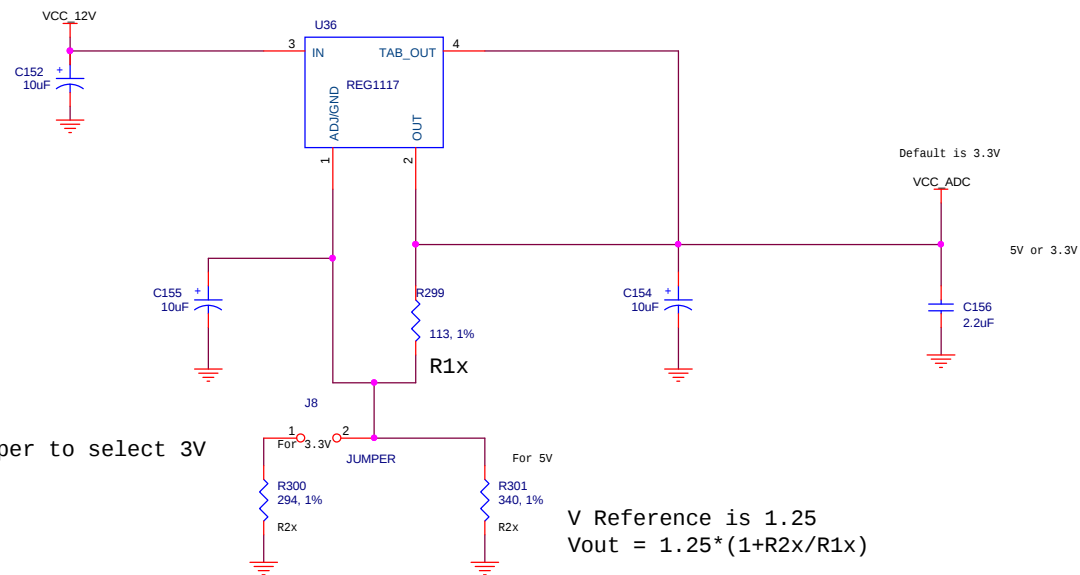
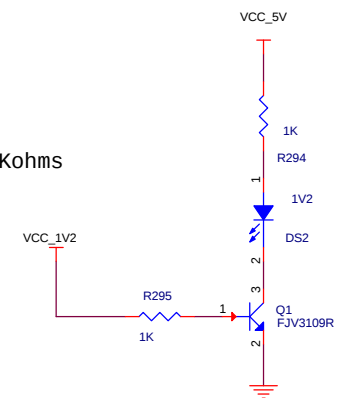
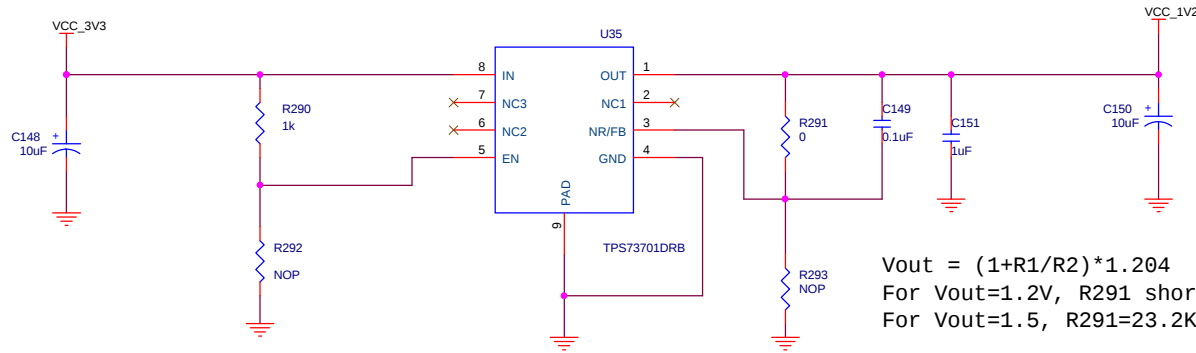
21 ARM\_JTAG\_RESETn  
21 MIPI\_JTAG\_RESETn  
22 RTP\_JTAG\_RESETn  
  
19,24,28,7 XDS\_JTAG\_RESETn

If VCC\_3.3V below 3.0V --> RESET

If VCC\_1.5V below 1.35V --> RESET

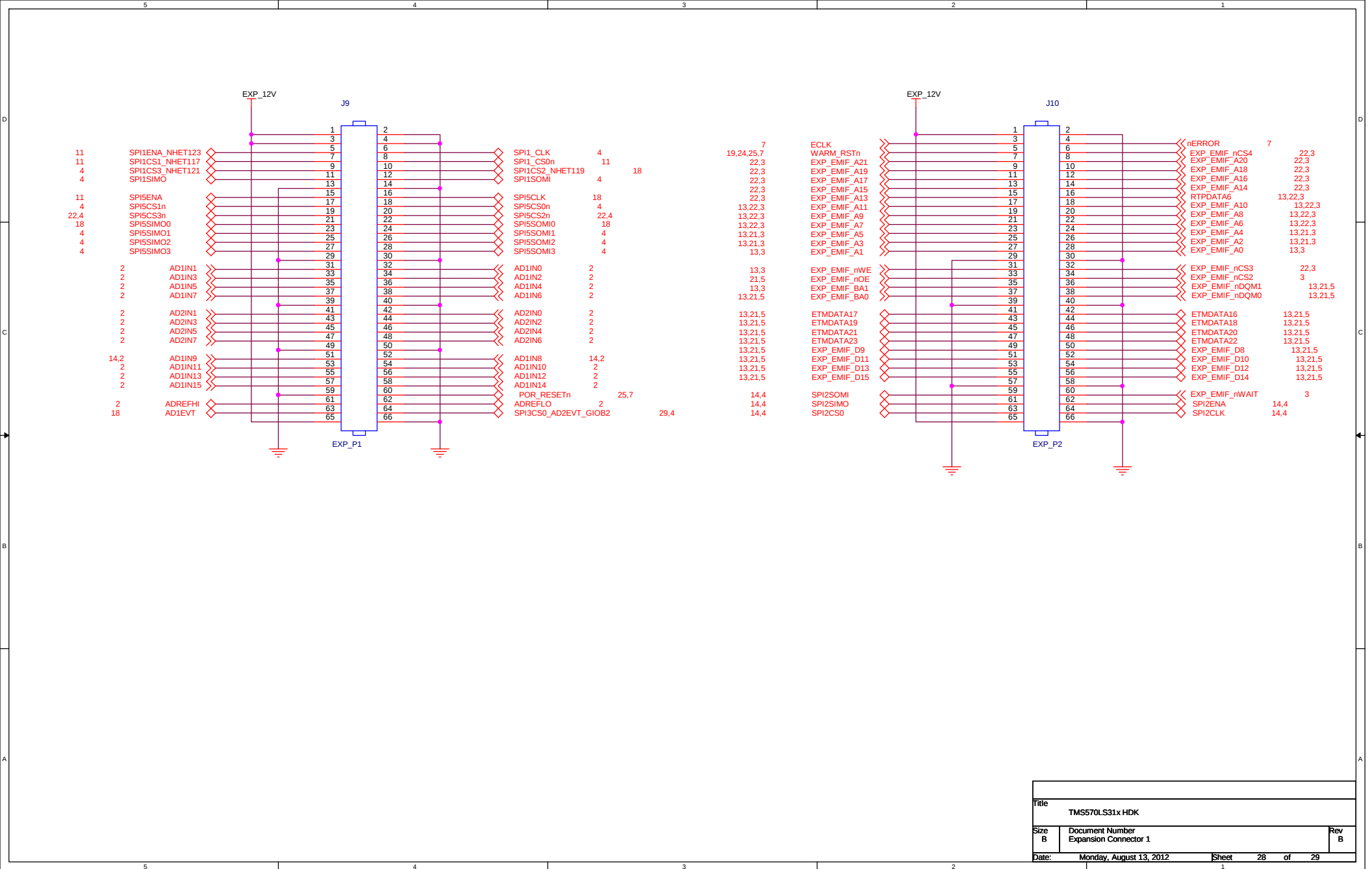
SENSE THRESHOLD FOR  
TPS3808G09 IS 0.840 VOLTS

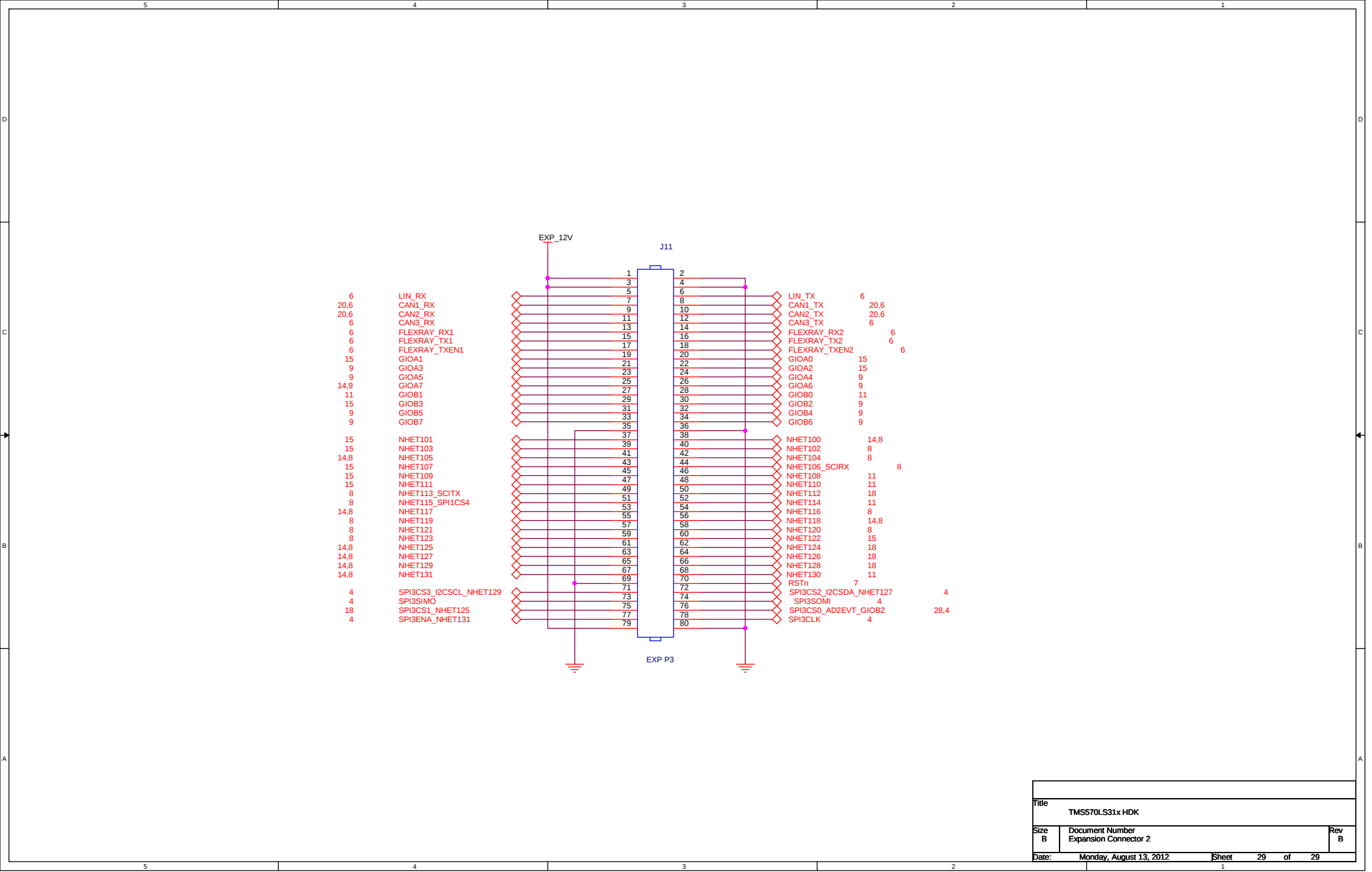
|       |                         |  |                 |    |       |
|-------|-------------------------|--|-----------------|----|-------|
| Title |                         |  | TMS570LS31x HDK |    |       |
| Size  | Document Number         |  |                 |    | Rev   |
| B     | RESET                   |  |                 |    | B     |
| Date: | Monday, August 13, 2012 |  | Sheet           | 25 | of 29 |



|                 |                         |                |
|-----------------|-------------------------|----------------|
| Title           |                         |                |
| TMS570LS31x HDK |                         |                |
| Size            | Document Number         | Rev            |
| B               | Power Supply            | C              |
| Date:           | Monday, August 13, 2012 | Sheet 26 of 29 |







|                 |                         |                |
|-----------------|-------------------------|----------------|
| Title           |                         |                |
| TMS570LS31x HDK |                         |                |
| Size            | Document Number         | Rev            |
| B               | Expansion Connector 2   | B              |
| Date:           | Monday, August 13, 2012 | Sheet 29 of 29 |

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